



European Space Research
and Technology Centre
Keplerlaan 1
2201 AZ Noordwijk
The Netherlands
T +31 (0)71 565 6565
F +31 (0)71 565 6040
www.esa.int

Systronic
Att. Mr P Pernot
6, avenue de l'atlantique
Z.A. Courtaboeuf
91955 Les Ulis Cedex
France

Our ref.

ESA-TECMSP-LE-005574

A handwritten signature in blue ink, appearing to be 'T Ghidini', is written over a large, light blue arrow pointing towards the left.

Noordwijk, 22/5/2017

VISA: T Ghidini (TEC-MSP)

Subject: Qualification Status of Systronic

Dear Mr Pernot,

Systronic submitted a rigid epoxy PCB for qualification renewal to ESA in Jan 2016. The results are reported in ESA-TEC-QTM-LAB-RP-004092.

The sample shows insufficient tin-lead thickness on through-hole surface pads, which is a nonconformance as per 7.3.4.3.2.g from ECSS-Q-ST-70-10C. The through-holes were submitted to solderability testing with acceptable results. The issue has been further evaluated as conform to table 10-12 from the new draft ECSS-Q-ST-70-60. Furthermore, Systronic responded to the corrective actions requested in ESA-TECMSP-LE-004351 showing the evaluation of new samples by Systronic as well as by a third party. The outcome of these evaluations have been found acceptable.

Systronic is considered qualified in accordance with ECSS-Q-ST-70-10C for the manufacture of Printed Circuit Boards as follows:

- Rigid non-sequential high Tg epoxy PCBs in accordance with PID 1 v9 **until 1 Jun 2018**

Best regards,

A handwritten signature in blue ink, appearing to be 'Stan Heltzel', is written over a large, light blue arrow pointing towards the left.

Stan Heltzel
Materials and Processes Section